FMC ADC guidelines to ease routing.
warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its
Sheet: 4

Label "GND" by Pin 7, 3.3V

TBD: Add alternate page connections for SPI, JTAG, and data out.

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Label "GND" by Pin 9

The interface is configured

by 3.3V to 1.5V level

by 3.3V to 1.8V level
Place at least two of the GND test points in the power section.

PCB Label

1. PCB Number: 600964
   PCB Rev: A

2. PCB LOGO
   ESD Susceptible

3. Texas Instruments

Assembly Notes:

ZZ1
This Assembly Note is for PCB labels only

ZZ2
ESD sensitive, ESD precautions shall be observed.

ZZ3
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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